

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV62565DBVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV62565DBVR	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DBV 5	2.9x1.6x1.45	16.9

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.063018	99.984134	999841	0.371908	3719
Not Categorized	Proprietary Materials		0.00001	0.015866	159	0.000059	1
Sub-Total			0.063028	100	1000000	0.371967	3720
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.128919	73.000153	730002	0.76083	7608
Thermoplastics	Epoxy	85954-11-6	0.047682	26.999847	269998	0.281401	2814
Sub-Total			0.176601	100	1000000	1.042231	10422
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	4.523069	97.374984	973750	26.6934	266934
Copper and Its Alloys	Iron	7439-89-6	0.12077	2.599999	26000	0.712738	7127
Copper and Its Alloys	Phosphorus	7723-14-0	0.000697	0.015005	150	0.004113	41
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.000465	0.010011	100	0.002744	27
Sub-Total			4.645001	100	1000000	27.412995	274130
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.04756	95.12	951200	0.280681	2807
Precious Metals	Gold	7440-57-5	0.00039	0.78	7800	0.002302	23
Precious Metals	Palladium	7440-05-3	0.00205	4.1	41000	0.012098	121
Sub-Total			0.05	100	1000000	0.295081	2951
Mold Compound							
Ceramics / Glass	Trimethoxy Silane	2530-83-8	0.005752	0.050001	500	0.033946	339
Other Inorganic Materials	Fused Silica	60676-86-0	0.011504	0.100001	1000	0.067892	679
Other Inorganic Materials	Silica	7631-86-9	9.922081	86.25	862500	58.556276	585563
Other Plastics and Rubber	Carbon Black	1333-86-4	0.057519	0.499997	5000	0.339455	3395
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.005752	0.050001	500	0.033946	339
Other Plastics and Rubber	Silicone	218163-11-2	0.005752	0.050001	500	0.033946	339
Thermoplastics	Epoxy	85954-11-6	1.495502	12.999999	130000	8.825873	88259
Sub-Total			11.503862	100	1000000	67.891334	678913
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.50603	100	1000000	2.986393	29864
Sub-Total			0.50603	100	1000000	2.986393	29864
Total			16.944522			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.